

Bill of Materials

TI DESIGNS

Part #

Literature #

DESIGNATOR	QUANTITY	VALUE	DESCRIPTION	SIZE	PART NUMBER	MANUFACTURER
U1	1	LMH6629	General Purpose FET-Input Operational Amplifier	SOT23-6	LMH6629IDBV	TI
U2, U3	2	OPA684ID	Precision High-Speed Difet(R) Operation Amplifier	SO-8	OPA684ID	TI
R1	1	27	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R2	1	1k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R3,R9,R11,R12	4	100	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R4	1	20.5	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R5,R8	2	1.3k	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R7	1	24.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
R13	1	49.9	Resistor, Chip, 1/16W, 1%	0603	Std	Std
C2,C3,C6,C7,C10,C11	6	100nF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
C1,C4,C8	3	10uF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
C5,C9	2	106pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
C12	1	20pF	Capacitor, Ceramic, 50V, X7R, 10%	0603	Std	Std
C13,C14	2	10uF	Capacitor, Tantalum, 50V, X7R, 10%	1206	Std	Std
L1,L2,L3,L4	4	1uH	Inductor	0805	0805LS-102XJLB	Coilcraft
VG1,SIG3_Out	2		SMA or SMB Board Jack		142-0701-801	Johnson
P1	1		Terminal Block, 2.5mm Centers		ED555/3DS	On-Shore

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